



Click [here](#) for the 3D model.

General Information

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|--------------------------|---|
| Series | SMD Comm X8G HT150C Flex |
| Style | SMD Chip |
| Description | SMD, MLCC, High Temperature, Ultra-Stable |
| Features | High Temperature, Ultra-Stable |
| RoHS | Yes |
| Termination | Flexible Termination |
| Marking | No |
| AEC-Q200 | No |
| Typical Component Weight | 4.6 mg |
| Shelf Life | 78 Weeks |
| MSL | 1 |

Dimensions

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|-----------|------------------|
| Chip Size | 0603 |
| L | 1.6mm +/-0.17mm |
| W | 0.8mm +/-0.15mm |
| T | 0.8mm +/-0.15mm |
| S | 0.4mm MIN |
| B | 0.45mm +/-0.15mm |

Packaging Specifications

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|--------------------|------------------------|
| Packaging | T&R, 330mm, Paper Tape |
| Packaging Quantity | 15000 |

Specifications

| | |
|--|---|
| Capacitance | 1.2 pF |
| Measurement Condition | 1 MHz 1.0Vrms |
| Tolerance | +/-0.1 pF |
| Voltage DC | 250 VDC |
| Dielectric Withstanding Voltage | 625 VDC |
| Temperature Range | -55/+150°C |
| Temp. Coefficient | X8G |
| Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC) | 30 ppm/C, 1MHz 1.0Vrms |
| Dissipation Factor | 0.1% 1 MHz 1.0Vrms |
| Aging Rate | 0% Loss/Decade Hour: Referee Time is 1000 Hours |
| Insulation Resistance | 100 GOhms |

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